

2. Hardware Specifications

Types	Specification parameters
CPU	Rockchip RK3288 (28nm HKMG process)
Processor	ARM® Cortex-A17 Quad-core processor, clocked up to 1.8GHz
GPU	ARM® Mali-T760 MP4 Quad-core GPU with AFBC (Frame Buffer Compression) Support OpenGL ES1.1/2.0/3.0/3.1, OpenVG1.1, OpenCL, DX11 Embedded high-performance 2D acceleration hardware
Video	Support 4K 10bits VP9/H265/H264 video decoding up to 60fps 1080P multi-format video decoding (VC-1, MPEG-1/2/4, VP8) 1080P video encoding, support H.264, VP8 format Video post processor: deinterlacing, denoising, edge/detail/color optimization
PMU	ACT8846 PMU Power Management Unit
DDR	Dual channel 64Bit DDR3-1333MHz (1GB/2GB/4GB Optional)
Memory	High-speed eMMC 5.1 (8GB/16GB/32GB/128GBOptional)
System	Android 5.1 / Ubuntu 14.04 / Ubuntu 16.04 / Linux
Power	Input voltage 5V, peak current 2.5A
WiFi	With SDIO interface for extending WiFi & Bluetooth combo module
Network	Onboard 10/100/1000Mbps Ethernet controller (Realtek RTL8211E)
Display	Video output interface: : - 1 x HDMI 2.0 , Support 4K@60fpsOutput and HDCP 1.4/2.2 Display interface (supports dual-screen display, dual-screen display): - 1 x dual channel MIPI-DSI

	<ul style="list-style-type: none"> - 1 x dual channel LVDS or RGB - 1 x eDP
Audio	<ul style="list-style-type: none"> 1 x HDMI audio output 1 x SPDIF digital audio interface for audio output 1 x I2S for audio input and output, (support 8 channels)
Camera	<ul style="list-style-type: none"> 1 x MIPI-CSI Camera Interface (Built-in Hardware ISP up to 13Mpixel) 1 x DVP Camera Interface (up to 5Mpixel)
USB	1 x USB 2.0 , 1 x USB 1.0 , 1 x USB 2.0 OTG
Extension ports	SDMMC, I2C, I2S, SPI, UART, ADC, PWM, GPIO
Infrared	1 x infrared receiver interface (occupied PWM0 pin)
Others	<ul style="list-style-type: none"> 4 x UART (UART2 defaults to Debug Serial) 2 x SDIO (SDIO0 is used to extend the WiFi module) 1 x SDMMC (for expansion TF card) 4 x PWM (PWM0 is used for infrared reception, and PWM2~3 is multiplexed with UART2) 5 x I2C, 3 x I2S, 2 x SPI, GPIO up to 55
Size	The size of core-board : 82mm x 60mm
Interface Type	MXM3.0 (314 PIN , 0.5mm interval)
PCB specifications	Board thickness 1.2mm, 6-layer board design, gold sinking process
Weight	21g